TOSHIBA Field Effect Transistor Silicon P Channel MOS Type ( $L^2$ - $\pi$ -MOSV)

## **2SJ402**

# DC-DC Converter, Relay Drive and Motor Drive Applications

• 4 V gate drive

• Low drain–source ON resistance :  $R_{DS}$  (ON) = 29 m $\Omega$  (typ.)

• High forward transfer admittance  $: |Y_{fs}| = 23 S (typ.)$ 

• Low leakage current  $: I_{DSS} = -100 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = -60 \,\text{V})$ 

• Enhancement-mode :  $V_{th} = -0.8 \sim -2.0 \text{ V (V}_{DS} = -10 \text{ V, I}_{D} = -1 \text{ mA})$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	-60	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	-60	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	ΙD	-30	Α	
	Pulse(Note 1)	I <sub>DP</sub>	-120	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	100	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	936	mJ	
Avalanche current		I <sub>AR</sub>	-30	Α	
Repetitive avalenche e	nergy (Note 3)	E <sub>AR</sub>	10	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.25	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

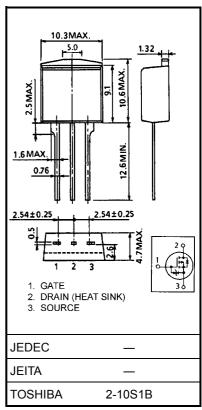
Note 2:  $V_{DD}$  = -50 V,  $T_{ch}$  = 25°C (initial), L = 747  $\mu$ H,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = -30 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

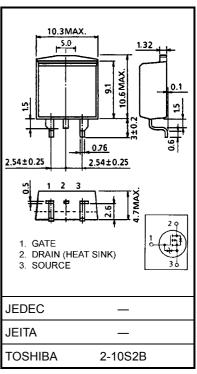
This transistor is an electrostatic sensitive device.

Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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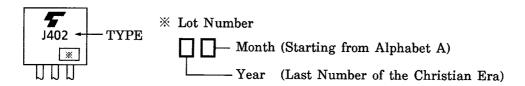
### **Electrical Characteristics (Ta = 25°C)**

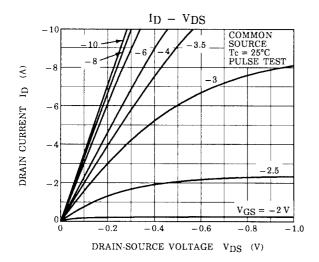
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V	_	_	-100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-60	_	1	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 mA	-0.8	_	-2.0	V
Drain-source ON resistance		R <sub>DS</sub> (ON)	V <sub>GS</sub> = -4 V, I <sub>D</sub> = -15 A	_	46	60	mΩ
			V <sub>GS</sub> = -10 V, I <sub>D</sub> = -15 A	_	29	38	11117
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -15 A	14	23	_	S
Input capacitano	е	C <sub>iss</sub>			3300	_	
Reverse transfer	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = −10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	460	_	pF
Output capacitance		Coss			1450	-	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = 10V$ $V_{DD} = -30V$ $V_{DD} = -30V$	_	20	_	ns
	Turn-on time	t <sub>on</sub>		_	25	_	
	Fall time	t <sub>f</sub>		_	35	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$	_	130	-	
Total gate charge (Gate-source plus gate-drain)		Qg		_	110		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx -48 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}$		75	_	nC -
Gate-drain ("mil	Gate-drain ("miller") charge				35	_	

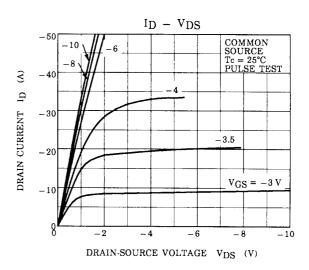
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

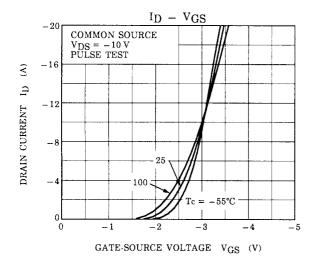
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	-30	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>		_	_	-120	Α
Forward voltage (diode)	$V_{DSF}$	$I_{DR} = -30 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = -30 A, V <sub>GS</sub> = 0 V	1	100		ns
Reverse recovery charge	Qrr	$dI_{DR}$ / $dt = 50 \text{ A}$ / $\mu$ S	_	0.16	_	μC

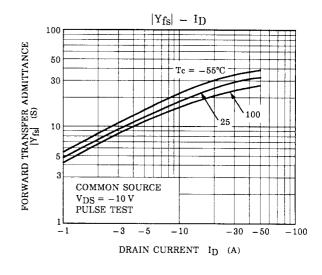
## Marking

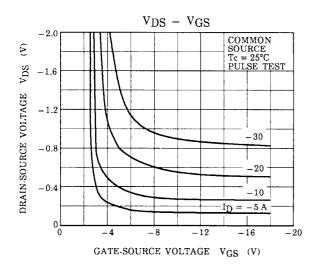


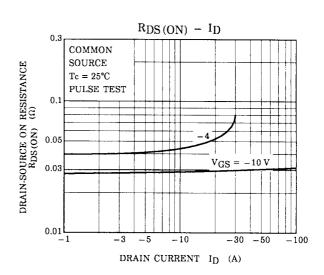




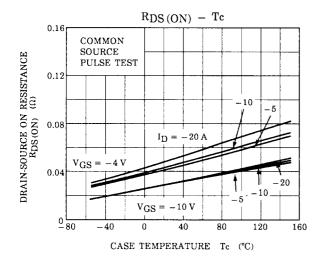


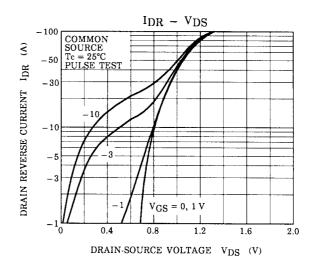


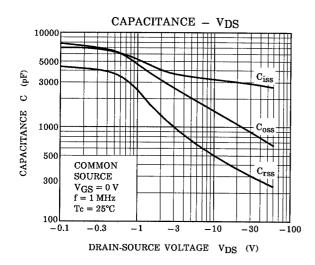


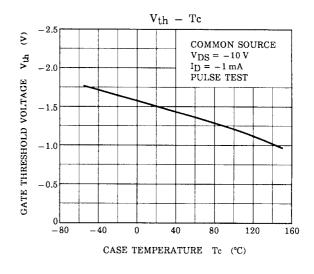


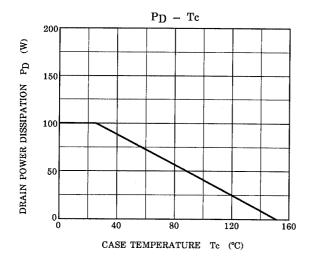
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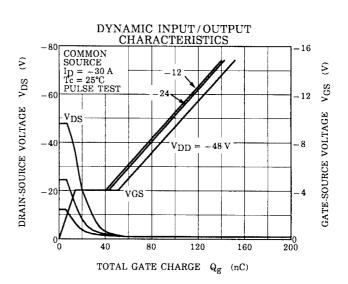




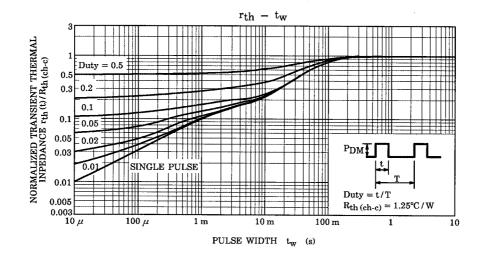


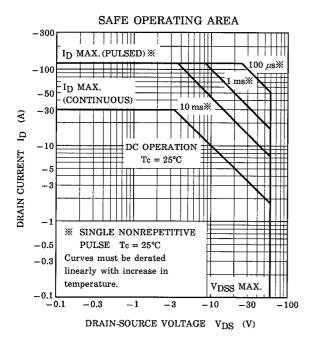


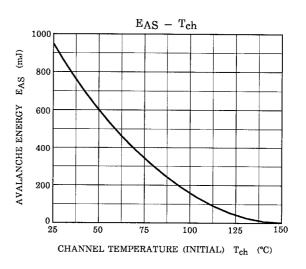


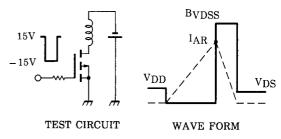


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$$\begin{array}{ll} R_G = 25\Omega \\ V_{DD} = -50V, \ L = 747 \mu H \end{array} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot (\frac{B_{VDSS}}{B_{VDSS} - V_{DD}}) \end{array}$$

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